SiHH24N65EF

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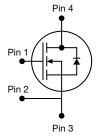
Vishay Siliconix

E Series Power MOSFET with Fast Body Diode

PRODUCT SUMMARY						
V _{DS} (V) at T _J max.	700					
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.137				
Q _g max. (nC)	117					
Q _{gs} (nC)	18					
Q _{gd} (nC)	33					
Configuration	Single					

PowerPAK[®] 8 x 8





N-Channel MOSFET

FEATURES

- Completely lead (Pb)-free device
- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)
- Kelvin connection for reduced noise
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH24N65EF-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			LIMIT	UNIT		
Drain-Source Voltage	V _{DS}	650	V			
Gate-Source Voltage	V _{GS}	± 30	v			
Continuous Drain Current (T _J = 150 °C)	V_{GS} at 10 V $\frac{T_{C} = 25^{\circ}}{T_{C} = 100}$	C L	23			
	V_{GS} at 10 V $T_{C} = 100$	°C I _D	14	А		
Pulsed Drain Current ^a	I _{DM}	55				
Linear Derating Factor		1.61	W/°C			
Single Pulse Avalanche Energy ^b	E _{AS}	353	mJ			
Maximum Power Dissipation	PD	202	W			
Operating Junction and Storage Temperature R	T _J , T _{stg}	-55 to +150	°C			
Drain-Source Voltage Slope	T _J = 125 °C	dV/dt	70	V/ns		
Reverse Diode dV/dt ^c		13	v/ns			

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 5 A.
- c. $I_{SD} \leq I_D,\, dI/dt$ = 100 A/µs, starting T_J = 25 °C.



RoHS COMPLIANT HALOGEN FREE



THERMAL RESISTANCE RATI	NGS								
PARAMETER	SYMBOL	TYP.		MAX.		UNIT			
Maximum Junction-to-Ambient	R _{thJA}	38 50			20.44				
Maximum Junction-to-Case (Drain)	R _{thJC}	0.48 0.62			°C/W				
SPECIFICATIONS (T _J = 25 °C, u	nless otherwi	se noted)							
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT	
Static					•				
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	250 µA	650	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	I _D = 10 mA	-	0.65	-	V/°C	
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V_{GS} , $I_D = 2$	250 µA	2.0	-	4.0	V	
Onto Course Lookage		Ň	$V_{\rm GS} = \pm 20$	V	-	-	± 100	nA	
Gate-Source Leakage	I _{GSS}	Ň	/ _{GS} = ± 30	V	-	-	± 1	μA	
		V _{DS} =	520 V, V _G	_S = 0 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 520 V	, V _{GS} = 0 V	∕, T _J = 125 °C	-	-	500	μA	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	ار	_D = 12 A	-	0.137	0.158	Ω	
Forward Transconductance	9 _{fs}	V _{DS} :	= 30 V, I _D =	= 12 A	-	9.3	-	S	
Dynamic									
Input Capacitance	C _{iss}		$V_{GS} = 0 V$		-	2780	-		
Output Capacitance	C _{oss}	٠ ١	$V_{\rm DS} = 100^{\circ}$, V,	-	131	-	1	
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		-	4	-	1		
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	$V_{DS} = 0$ V to 520 V, $V_{GS} = 0$ V		-	88	-	pF		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	359	-			
Total Gate Charge	Qq				-	78	117	nC	
Gate-Source Charge	Q _{qs}	V _{GS} = 10 V	I _D = 12	A, V _{DS} = 520 V	-	18	-		
Gate-Drain Charge	Q _{gd}				-	33	-		
Turn-On Delay Time	t _{d(on)}				-	28	56		
Rise Time	t _r	V _{DD} =	520 V, I _D :	= 12 A,	-	51	77	ns	
Turn-Off Delay Time	t _{d(off)}	V _{GS} =	= 10 V, R _g =	= 9.1 Ω	-	83	125		
Fall Time	t _f	1			-	50	75	1	
Gate Input Resistance	Rg	f = 1 MHz, open drain		0.27	0.53	1.10	Ω		
Drain-Source Body Diode Characteristic	s								
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	23	А		
Pulsed Diode Forward Current	I _{SM}			-	-	55			
Diode Forward Voltage	V _{SD}	T _J = 25 °C	C, I _S = 12 A	, V _{GS} = 0 V	-	0.95	1.2	V	
Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 12 \text{ A},$ dl/dt = 100 A/µs, V _R = 25 V		-	145	290	ns		
Reverse Recovery Charge	Q _{rr}			-	0.91	1.82	μC		
Reverse Recovery Current	I _{RRM}			-	12	-	Α		

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .



SiHH24N65EF

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

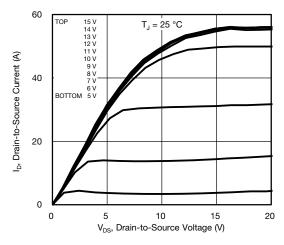


Fig. 1 - Typical Output Characteristics

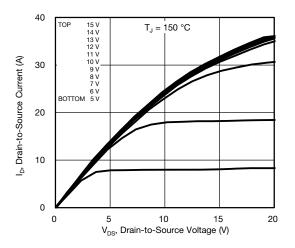


Fig. 2 - Typical Output Characteristics

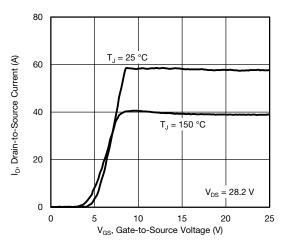


Fig. 3 - Typical Transfer Characteristics

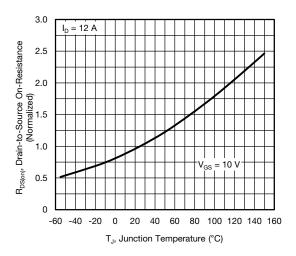


Fig. 4 - Normalized On-Resistance vs. Temperature

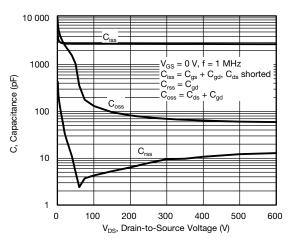


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

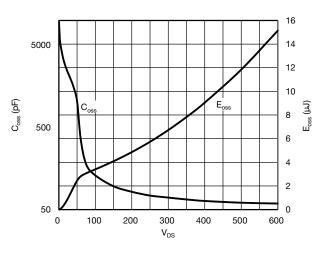


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}

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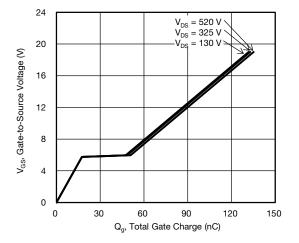


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

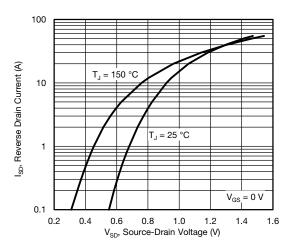


Fig. 8 - Typical Source-Drain Diode Forward Voltage

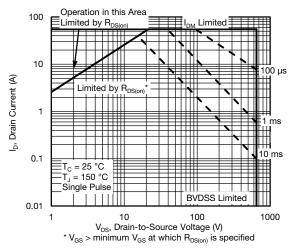


Fig. 9 - Maximum Safe Operating Area

875 Drain-to-Source Breakdown Voltage (V) 850 825 800 775 750 725 700 $\mathsf{V}_{\mathsf{DS}},$ $I_D = 10 \text{ mA}$ 675 -60 -40 -20 0 20 40 60 80 100 120 140 160 T_J, Junction Temperature (°C)

Fig. 10 - Maximum Drain Current vs. Case Temperature

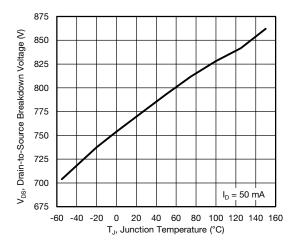
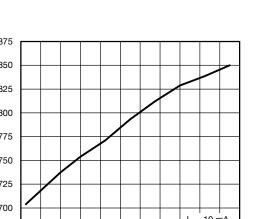


Fig. 11 - Temperature vs. Drain-to-Source Voltage



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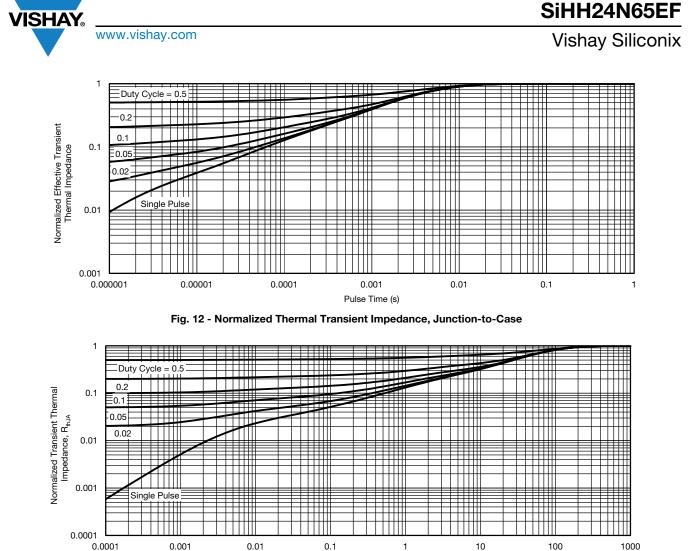


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

Pulse Time (s)

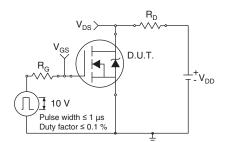


Fig. 14 - Switching Time Test Circuit

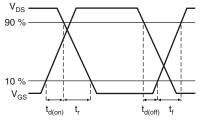


Fig. 15 - Switching Time Waveforms

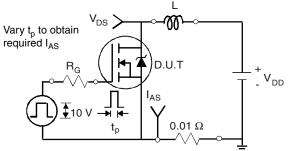


Fig. 16 - Unclamped Inductive Test Circuit

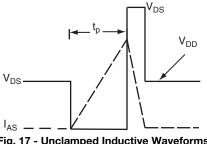
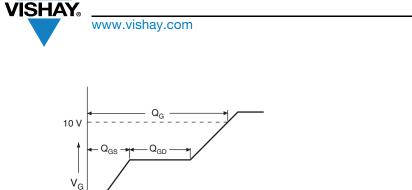


Fig. 17 - Unclamped Inductive Waveforms

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Charge —

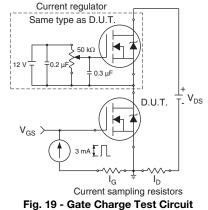
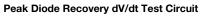


Fig. 18 - Basic Gate Charge Waveform



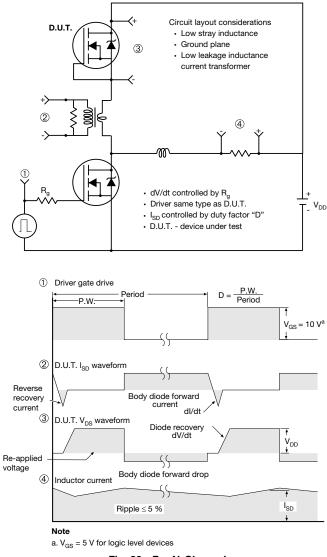


Fig. 20 - For N-Channel

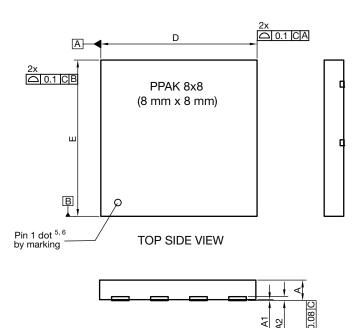
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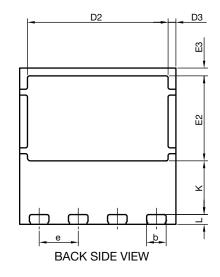
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PowerPAK[®] 8 x 8 Case Outline





DIM.	MILLIMETERS			INCHES			
Dilvi.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A ⁸	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2		020 ref.		0.008 ref.			
b ⁴	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3		0.40 BSC			0.016 BSC		
e	2.00 BSC		0.079 BSC				
E	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3	0.40 BSC			0.016 BSC			
К	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N ³	8				8		

D

Notes

1. Use millimeters as the primary measurement.

2. Dimensioning and tolerances conform to ASME Y14.5 M - 1994.

3. N is the number of terminals.

4. Package warpage max. 0.08 mm.

5. The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body.

6. Exact shape and size of this feature is optional.

ECN: T15-0225-Rev. A, 18-May-15 DWG: 6041

Revision: 18-May-15

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Recommended Minimum PADs for PowerPAK[®] 8 mm x 8 mm



Dimensions in millimeters

Document Number: 68441



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